

SN54ALS645A, SN54AS645, SN74ALS645A, SN74AS645 OCTAL BUS TRANSCEIVERS WITH 3-STATE OUTPUTS

SDAS278 – JANUARY 1995

- Bidirectional Bus Transceivers in High-Density 20-Pin Packages
- True Logic
- 3-State Outputs
- Package Options Include Plastic Small-Outline (DW) Packages, Ceramic Chip Carriers (FK), and Standard Plastic (N) and Ceramic (J) 300-mil DIPs

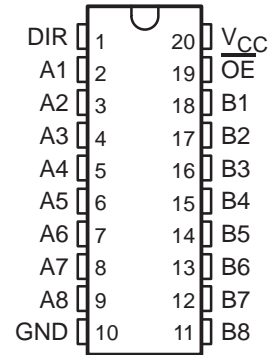
description

These octal bus transceivers are designed for asynchronous two-way communication between data buses. These devices transmit data from the A bus to the B bus or from the B bus to the A bus, depending on the level at the direction-control (DIR) input. The output-enable (\overline{OE}) input can be used to disable the device so that the buses are effectively isolated.

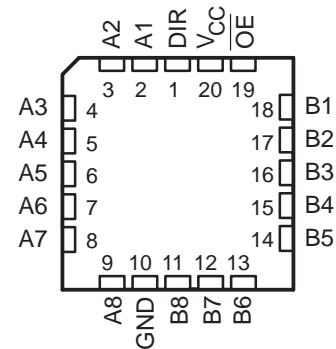
The -1 version of the SN74ALS645A is identical to the standard version, except that the recommended maximum I_{OL} is increased to 48 mA. There is no -1 version of the SN54ALS645A.

The SN54ALS645A and SN54AS645 are characterized for operation over the full military temperature range of -55°C to 125°C . The SN74ALS645A and SN74AS645 are characterized for operation from 0°C to 70°C .

SN54ALS645A, SN54AS645 . . . J PACKAGE
SN74ALS645A, SN74AS645 . . . DW OR N PACKAGE
(TOP VIEW)



SN54ALS645A, SN54AS645 . . . FK PACKAGE
(TOP VIEW)



FUNCTION TABLE

INPUTS		OPERATION
\overline{OE}	DIR	
L	L	B data to A bus
L	H	A data to B bus
H	X	Isolation

SN54ALS645A, SN54AS645, SN74ALS645A, SN74AS645
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WITH 3-STATE OUTPUTS

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electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER	TEST CONDITIONS	SN54ALS645A		SN74ALS645A		UNIT	
		MIN	TYP†	MAX	MIN		TYP†
V_{IK}	$V_{CC} = 4.5\text{ V}$, $I_I = -18\text{ mA}$			-1.5		-1.5	V
V_{OH}	$V_{CC} = 4.5\text{ V to }5.5\text{ V}$, $I_{OH} = -0.4\text{ mA}$	$V_{CC} - 2$		$V_{CC} - 2$		V	
	$V_{CC} = 4.5\text{ V}$	$I_{OH} = -3\text{ mA}$	2.4	3.2	2.4		3.2
		$I_{OH} = -12\text{ mA}$	2				
V_{OL}	$V_{CC} = 4.5\text{ V}$	$I_{OL} = 12\text{ mA}$	0.25	0.4	0.25	0.4	V
		$I_{OL} = 24\text{ mA}$			0.35	0.5	
		$I_{OL} = 48\text{ mA}^\ddagger$			0.35	0.5	
I_I	Control inputs	$V_{CC} = 5.5\text{ V}$	$V_I = 7\text{ V}$	0.1		0.1	mA
	A or B ports		$V_I = 5.5\text{ V}$	0.1		0.1	
I_{IH}	Control inputs	$V_{CC} = 5.5\text{ V}$, $V_I = 2.7\text{ V}$	20		20		μA
	A or B ports§		20		20		
I_{IL}	Control inputs	$V_{CC} = 5.5\text{ V}$, $V_I = 0.4\text{ V}$	-0.1		-0.1		mA
	A or B ports§		-0.1		-0.1		
I_{O}^\parallel	$V_{CC} = 5.5\text{ V}$, $V_O = 2.25\text{ V}$	-20	-112	-30	-112	mA	
I_{CC}	$V_{CC} = 5.5\text{ V}$	Outputs high	30	48	30	45	mA
		Outputs low	36	60	36	55	
		Outputs disabled	38	63	38	58	

† All typical values are at $V_{CC} = 5\text{ V}$, $T_A = 25^\circ\text{C}$.

‡ Applies only to the -1 version and only if V_{CC} is between 4.75 V and 5.25 V

§ For I/O ports, the parameters I_{IH} and I_{IL} include the off-state output current.

¶ The output conditions have been chosen to produce a current that closely approximates one half of the true short-circuit output current, I_{OS} .

switching characteristics (see Figure 1)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	$V_{CC} = 4.5\text{ V to }5.5\text{ V}$, $C_L = 50\text{ pF}$, $R_1 = 500\ \Omega$, $R_2 = 500\ \Omega$, $T_A = \text{MIN to MAX}^\#$				UNIT
			SN54ALS645A		SN74ALS645A		
			MIN	MAX	MIN	MAX	
t_{PLH}	A or B	B or A	1	19	3	10	ns
t_{PHL}			1	14	3	10	
t_{PZH}	\overline{OE}	A or B	2	30	5	20	ns
t_{PZL}			2	29	5	20	
t_{PHZ}	\overline{OE}	A or B	2	14	2	10	ns
t_{PLZ}			2	30	4	15	

For conditions shown as MIN or MAX, use the appropriate value specified under recommended operating conditions.

SN54ALS645A, SN54AS645, SN74ALS645A, SN74AS645

OCTAL BUS TRANSCEIVERS

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absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Supply voltage, V_{CC}	7 V
Input voltage, V_I : All inputs	7 V
I/O ports	5.5 V
Operating free-air temperature range, T_A : SN54AS645	-55°C to 125°C
SN74AS645	0°C to 70°C
Storage temperature range	-65°C to 150°C

† Stresses beyond those listed under “absolute maximum ratings” may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under “recommended operating conditions” is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

recommended operating conditions

		SN54AS645			SN74AS645			UNIT
		MIN	NOM	MAX	MIN	NOM	MAX	
V_{CC}	Supply voltage	4.5	5	5.5	4.5	5	5.5	V
V_{IH}	High-level input voltage	2			2			V
V_{IL}	Low-level input voltage			0.8			0.8	V
I_{OH}	High-level output current			-12			-15	mA
I_{OL}	Low-level output current			48			64	mA
T_A	Operating free-air temperature	-55		125	0		70	°C

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER	TEST CONDITIONS	SN54AS645			SN74AS645			UNIT
		MIN	TYP‡	MAX	MIN	TYP‡	MAX	
V_{IK}	$V_{CC} = 4.5$ V, $I_I = -18$ mA			-1.2			-1.2	V
V_{OH}	$V_{CC} = 4.5$ V to 5.5 V, $I_{OH} = -2$ mA	$V_{CC} - 2$		$V_{CC} - 2$				V
	$V_{CC} = 4.5$ V, $I_{OH} = -3$ mA	2.4	3.2	2.4	3.2			
	$V_{CC} = 4.5$ V, $I_{OH} = -12$ mA	2.4						
	$V_{CC} = 4.5$ V, $I_{OH} = -15$ mA				2.4			
V_{OL}	$V_{CC} = 4.5$ V, $I_{OL} = 48$ mA		0.3	0.55				V
	$V_{CC} = 4.5$ V, $I_{OL} = 64$ mA				0.35	0.55		
I_I	Control inputs	$V_{CC} = 5.5$ V		$V_I = 7$ V		0.1		mA
	A or B ports	$V_{CC} = 5.5$ V		$V_I = 5.5$ V		0.1		
I_{IH}	Control inputs	$V_{CC} = 5.5$ V,		$V_I = 2.7$ V		20		μ A
	A or B ports§	$V_{CC} = 5.5$ V,		$V_I = 2.7$ V		70		
I_{IL}	Control inputs	$V_{CC} = 5.5$ V,		$V_I = 0.4$ V		-0.5		mA
	A or B ports§	$V_{CC} = 5.5$ V,		$V_I = 0.4$ V		-0.75		
I_{O}^{\parallel}	$V_{CC} = 5.5$ V, $V_O = 2.25$ V	-50		-150	-50		-150	mA
I_{CC}	$V_{CC} = 5.5$ V, Outputs high		62	97		62	97	mA
	$V_{CC} = 5.5$ V, Outputs low		95	149		95	149	
	$V_{CC} = 5.5$ V, Outputs disabled		79	123		79	123	

‡ All typical values are at $V_{CC} = 5$ V, $T_A = 25^\circ\text{C}$.

§ For I/O ports, the parameters I_{IH} and I_{IL} include the off-state output current.

¶ The output conditions have been chosen to produce a current that closely approximates one half of the true short-circuit output current, I_{OS} .



SN54ALS645A, SN54AS645, SN74ALS645A, SN74AS645
**OCTAL BUS TRANSCEIVERS
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switching characteristics (see Figure 1)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	V _{CC} = 4.5 V to 5.5 V, C _L = 50 pF, R ₁ = 500 Ω, R ₂ = 500 Ω, T _A = MIN to MAX†				UNIT
			SN54AS645		SN74AS645		
			MIN	MAX	MIN	MAX	
t _{PLH}	A or B	B or A	2	11	2	9.5	ns
t _{PHL}			2	10.5	2	9	
t _{PZH}	\overline{OE}	A or B	2	12	2	11	ns
t _{PZL}			2	12	2	10	
t _{PHZ}	\overline{OE}	A or B	2	8	2	7	ns
t _{PLZ}			2	13	2	12	

† For conditions shown as MIN or MAX, use the appropriate value specified under recommended operating conditions.

SN54ALS645A, SN54AS645, SN74ALS645A, SN74AS645 OCTAL BUS TRANSCEIVERS WITH 3-STATE OUTPUTS

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PARAMETER MEASUREMENT INFORMATION SERIES 54ALS/74ALS AND 54AS/74AS DEVICES



- NOTES: A. C_L includes probe and jig capacitance.
 B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
 C. When measuring propagation delay items of 3-state outputs, switch S1 is open.
 D. All input pulses have the following characteristics: $PRR \leq 1$ MHz, $t_r = t_f = 2$ ns, duty cycle = 50%.
 E. The outputs are measured one at a time with one transition per measurement.

Figure 1. Load Circuits and Voltage Waveforms

PACKAGING INFORMATION

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead/Ball Finish (6)	MSL Peak Temp (3)	Op Temp (°C)	Device Marking (4/5)	Samples
8403301RA	ACTIVE	CDIP	J	20	1	TBD	A42	N / A for Pkg Type	-55 to 125	8403301RA SNJ54ALS645AJ	Samples
8403301SA	ACTIVE	CFP	W	20	1	TBD	A42	N / A for Pkg Type	-55 to 125	8403301SA SNJ54ALS645AW	Samples
SN54ALS645AJ	ACTIVE	CDIP	J	20	1	TBD	A42	N / A for Pkg Type	-55 to 125	SN54ALS645AJ	Samples
SN54AS645J	ACTIVE	CDIP	J	20	1	TBD	A42	N / A for Pkg Type	-55 to 125	SN54AS645J	Samples
SN74ALS645A-1DW	ACTIVE	SOIC	DW	20	25	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	ALS645A-1	Samples
SN74ALS645A-1DWG4	ACTIVE	SOIC	DW	20	25	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	ALS645A-1	Samples
SN74ALS645A-1DWR	ACTIVE	SOIC	DW	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	ALS645A-1	Samples
SN74ALS645A-1N	ACTIVE	PDIP	N	20	20	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	0 to 70	SN74ALS645A-1N	Samples
SN74ALS645A-1N3	OBSOLETE	PDIP	N	20		TBD	Call TI	Call TI	0 to 70		
SN74ALS645A-1NE4	ACTIVE	PDIP	N	20	20	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	0 to 70	SN74ALS645A-1N	Samples
SN74ALS645A-1NSR	ACTIVE	SO	NS	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	ALS645A-1	Samples
SN74ALS645ADW	ACTIVE	SOIC	DW	20	25	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	ALS645A	Samples
SN74ALS645ADWR	ACTIVE	SOIC	DW	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	ALS645A	Samples
SN74ALS645AN	ACTIVE	PDIP	N	20	20	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	0 to 70	SN74ALS645AN	Samples
SN74ALS645AN3	OBSOLETE	PDIP	N	20		TBD	Call TI	Call TI	0 to 70		
SN74ALS645ANSR	ACTIVE	SO	NS	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	ALS645A	Samples
SN74AS645DW	ACTIVE	SOIC	DW	20	25	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	AS645	Samples
SN74AS645DWE4	ACTIVE	SOIC	DW	20	25	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	AS645	Samples

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead/Ball Finish (6)	MSL Peak Temp (3)	Op Temp (°C)	Device Marking (4/5)	Samples
SN74AS645N	ACTIVE	PDIP	N	20	20	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	0 to 70	SN74AS645N	Samples
SN74AS645NE4	ACTIVE	PDIP	N	20	20	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	0 to 70	SN74AS645N	Samples
SNJ54ALS645AJ	ACTIVE	CDIP	J	20	1	TBD	A42	N / A for Pkg Type	-55 to 125	8403301RA SNJ54ALS645AJ	Samples
SNJ54ALS645AW	ACTIVE	CFP	W	20	1	TBD	A42	N / A for Pkg Type	-55 to 125	8403301SA SNJ54ALS645AW	Samples
SNJ54AS645FK	OBSOLETE	LCCC	FK	20		TBD	Call TI	Call TI	-55 to 125		
SNJ54AS645J	ACTIVE	CDIP	J	20	1	TBD	A42	N / A for Pkg Type	-55 to 125	SNJ54AS645J	Samples

(1) The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check <http://www.ti.com/productcontent> for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

(3) MSL, Peak Temp. - The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

(4) There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.

(5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.

(6) Lead/Ball Finish - Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead/Ball Finish values may wrap to two lines if the finish value exceeds the maximum column width.

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OTHER QUALIFIED VERSIONS OF SN54ALS645A, SN54AS645, SN74ALS645A, SN74AS645 :

- Catalog: [SN74ALS645A](#), [SN74AS645](#)
- Military: [SN54ALS645A](#), [SN54AS645](#)

NOTE: Qualified Version Definitions:

- Catalog - TI's standard catalog product
- Military - QML certified for Military and Defense Applications

TAPE AND REEL INFORMATION

QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE


*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN74ALS645A-1DWR	SOIC	DW	20	2000	330.0	24.4	10.8	13.3	2.7	12.0	24.0	Q1
SN74ALS645A-1NSR	SO	NS	20	2000	330.0	24.4	9.0	13.0	2.4	4.0	24.0	Q1
SN74ALS645ADWR	SOIC	DW	20	2000	330.0	24.4	10.8	13.3	2.7	12.0	24.0	Q1
SN74ALS645ANSR	SO	NS	20	2000	330.0	24.4	9.0	13.0	2.4	4.0	24.0	Q1

TAPE AND REEL BOX DIMENSIONS



*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
SN74ALS645A-1DWR	SOIC	DW	20	2000	367.0	367.0	45.0
SN74ALS645A-1NSR	SO	NS	20	2000	367.0	367.0	45.0
SN74ALS645ADWR	SOIC	DW	20	2000	367.0	367.0	45.0
SN74ALS645ANSR	SO	NS	20	2000	367.0	367.0	45.0

J (R-GDIP-T**)

14 LEADS SHOWN

CERAMIC DUAL IN-LINE PACKAGE



DIM \ PINS **	14	16	18	20
A	0.300 (7,62) BSC	0.300 (7,62) BSC	0.300 (7,62) BSC	0.300 (7,62) BSC
B MAX	0.785 (19,94)	.840 (21,34)	0.960 (24,38)	1.060 (26,92)
B MIN	—	—	—	—
C MAX	0.300 (7,62)	0.300 (7,62)	0.310 (7,87)	0.300 (7,62)
C MIN	0.245 (6,22)	0.245 (6,22)	0.220 (5,59)	0.245 (6,22)



4040083/F 03/03

- NOTES:
- All linear dimensions are in inches (millimeters).
 - This drawing is subject to change without notice.
 - This package is hermetically sealed with a ceramic lid using glass frit.
 - Index point is provided on cap for terminal identification only on press ceramic glass frit seal only.
 - Falls within MIL STD 1835 GDIP1-T14, GDIP1-T16, GDIP1-T18 and GDIP1-T20.

W (R-GDFP-F20)

CERAMIC DUAL FLATPACK



- NOTES:
- A. All linear dimensions are in inches (millimeters).
 - B. This drawing is subject to change without notice.
 - C. This package can be hermetically sealed with a ceramic lid using glass frit.
 - D. Index point is provided on cap for terminal identification only.
 - E. Falls within Mil-Std 1835 GDFP2-F20

FK (S-CQCC-N**)

LEADLESS CERAMIC CHIP CARRIER

28 TERMINAL SHOWN



NO. OF TERMINALS **	A		B	
	MIN	MAX	MIN	MAX
20	0.342 (8,69)	0.358 (9,09)	0.307 (7,80)	0.358 (9,09)
28	0.442 (11,23)	0.458 (11,63)	0.406 (10,31)	0.458 (11,63)
44	0.640 (16,26)	0.660 (16,76)	0.495 (12,58)	0.560 (14,22)
52	0.740 (18,78)	0.761 (19,32)	0.495 (12,58)	0.560 (14,22)
68	0.938 (23,83)	0.962 (24,43)	0.850 (21,6)	0.858 (21,8)
84	1.141 (28,99)	1.165 (29,59)	1.047 (26,6)	1.063 (27,0)



4040140/D 01/11

- NOTES:
- All linear dimensions are in inches (millimeters).
 - This drawing is subject to change without notice.
 - This package can be hermetically sealed with a metal lid.
 - Falls within JEDEC MS-004

N (R-PDIP-T**)

PLASTIC DUAL-IN-LINE PACKAGE

16 PINS SHOWN



- NOTES:
- A. All linear dimensions are in inches (millimeters).
 - B. This drawing is subject to change without notice.
 - Falls within JEDEC MS-001, except 18 and 20 pin minimum body length (Dim A).
 - The 20 pin end lead shoulder width is a vendor option, either half or full width.

DW (R-PDSO-G20)

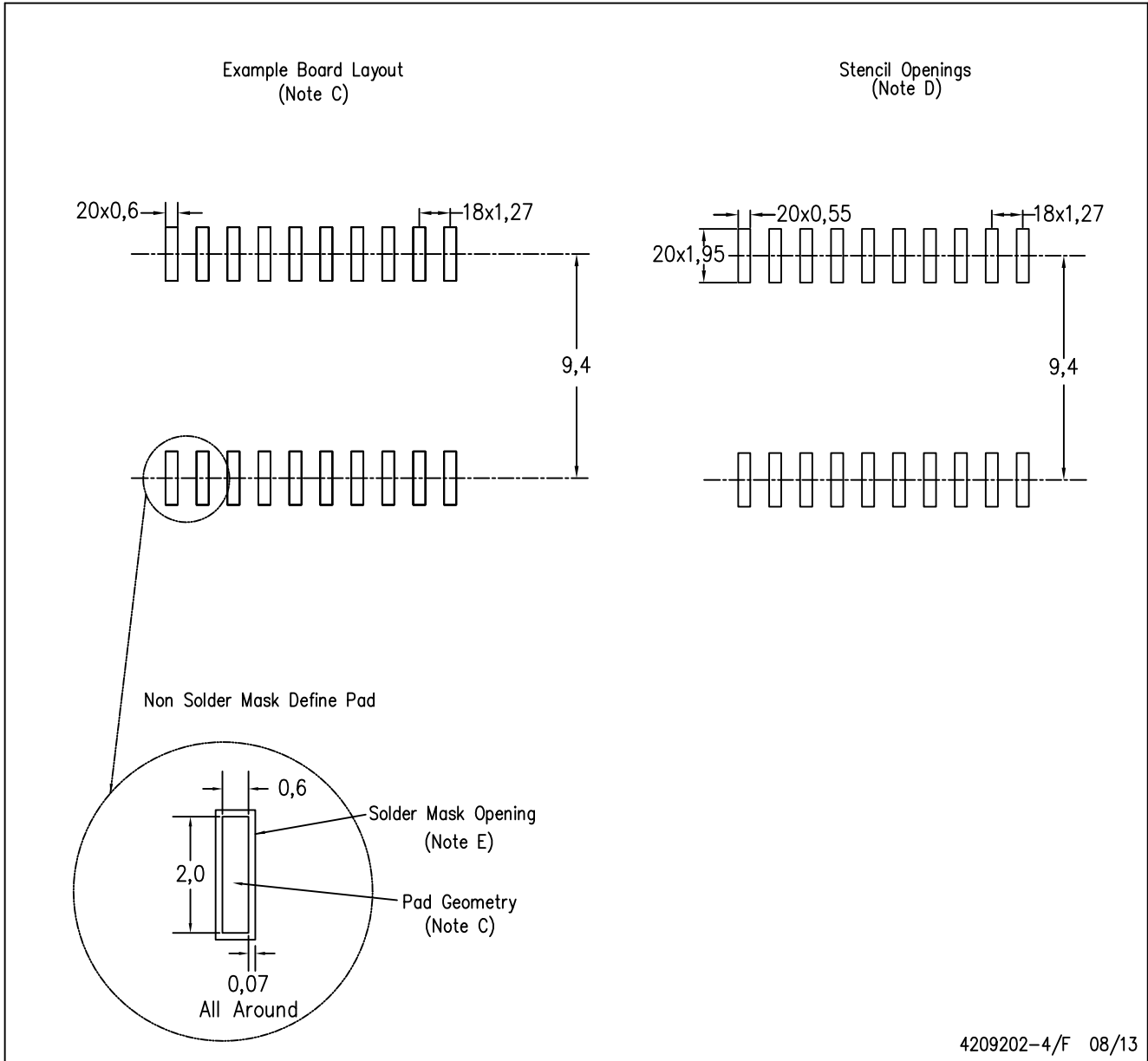
PLASTIC SMALL OUTLINE



- NOTES:
- A. All linear dimensions are in inches (millimeters). Dimensioning and tolerancing per ASME Y14.5M-1994.
 - B. This drawing is subject to change without notice.
 - C. Body dimensions do not include mold flash or protrusion not to exceed 0.006 (0,15).
 - D. Falls within JEDEC MS-013 variation AC.

DW (R-PDSO-G20)

PLASTIC SMALL OUTLINE



4209202-4/F 08/13

- NOTES:
- A. All linear dimensions are in millimeters.
 - B. This drawing is subject to change without notice.
 - C. Refer to IPC7351 for alternate board design.
 - D. Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC-7525
 - E. Customers should contact their board fabrication site for solder mask tolerances between and around signal pads.

MECHANICAL DATA

NS (R-PDSO-G**)

PLASTIC SMALL-OUTLINE PACKAGE

14-PINS SHOWN



- NOTES:
- A. All linear dimensions are in millimeters.
 - B. This drawing is subject to change without notice.
 - C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15.

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